

EV Group announces NanoCleave layer release new technology revolutionizing 3D Integration – January 30, 2024

EVG introduced NanoCleave™, a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory and power device formation, as well as semiconductor advanced packaging. NanoCleave is a fully front-end-compatible layer release technology that features an IR laser that can pass through silicon, which is transparent to the IR laser wavelength. Coupled with the use of specially formulated inorganic layers, this technology enables an IR laser-initiated release of any ultra-thin film or layer from silicon carriers with nanometer precision. “Semiconductor scaling has become increasingly complex and difficult to achieve due to tighter process tolerances.” stated Paul Lindner, executive technology director at EV Group.

The screenshot shows a news article on the EVG website. The main headline is "EVG, 3D 집적 혁신하는 NanoCleave 레이어 릴리즈 기술 발표" (EVG, 3D Integration Revolutionizing NanoCleave Layer Release Technology Announcement). The article text is in Korean and discusses the benefits of NanoCleave technology, such as enabling ultra-thin layer stacking and improving 3D integration. It mentions that the technology allows for the release of ultra-thin films or layers from silicon carriers with nanometer precision. The article also includes a photo of a laboratory setting with various pieces of equipment.

<https://www.electimes.com/news/articleView.html?idxno=332198>